



NEWS RELEASE

Mitsui Mining & Smelting Co., Ltd.
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Expansion works for additional MicroThin™ production in Japan plant
— Total 1.4million sqm/month capacity will be ready in 2014 Q2 after completion of the works —

Mitsui Mining & Smelting Co.,Ltd. (Head Office: Shinagawa-ku, Tokyo) has decided to increase a capacity of MicroThin™, ultra-thin electrodeposited copper foil with carrier which is used for IC substrate, from 1.0million sqm/month to 1.4million sqm/month at Ageo plant in Japan.

MicroThin™ is mainly used for IC substrate of application processor of smartphone. Higher functionality of smartphone leads highly integrated semiconductor and consequently a miniaturization of copper pattern of IC substrate is proceeding at a high pace.

MicroThin™ has thin copper foil thickness variation from 1.5um to 5um combined with several kinds of fine surface treatment to meet customer's requirement. And its possibility of making very fine pattern and availability of wide width (1300mm width) roll supply ability contributes to customer's productivity improvement. Accordingly demand to this foil is increasing sharply.

And for further ultra fine pattern, Mitsui has already launched "MFG series"(※ 1), which has coated primer resin(※ 2) on MicroThin™. It has been already used for some application processor of major smartphone and The demand growth is highly expected in the market.

In smartphone semiconductor market, further miniaturization and increasing demand are expected. And material supplier is required "stable quality", "Cutting edge technology" and "sufficient supply ability". To accelerate the quality improvement technical development based on close communication with customers, We decided to invest at our flag ship plant in Ageo, Japan.

The expansion works will be finished by March 2014 and the total capacity will increase from 1.0million /month to 1.4 million /month from April. And BCP operation(※ 3) start-up is still under careful investigation in line with the worldwide demand growth.

This investment enables Mitsui to meet growing market demand and to accelerate the new product development as well. And an impact to earnings forecasts by this investment is limited.

End

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(Note)

※ 1 MFG series

... The product which has coated 2um of primer resin on MicroThin™. To meet different type of copper patterning, 2 types of product has launched.

※ 2 Primer resin

... Resin to secure enough adhesive strength between copper foil and prepreg. Mitsui developed resin has both excellent bonding strength and ultra fine patterning.

※ 3 BCP line

... As for BCP (Business Continuity Planning), the production line which is installed in Malaysia factory. Please refer our previous press release “Backup system for producing MicroThin™, ultra-thin electrodeposited copper foil with carrier” on 7 July, 2011.